



## Material Content Data Sheet



<b>Sales Product Name</b>		2EDL05N06PF		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001135214						
<b>Package</b>		PG-DSO-8-53		<b>Weight*</b>		80.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	1.19	1.19	11865	11865
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105	
	non noble metal	zinc	7440-66-6	0.034	0.04		419	
	non noble metal	iron	7439-89-6	0.673	0.84		8388	
wire	non noble metal	copper	7440-50-8	27.330	34.06	34.95	340572	349484
	noble metal	gold	7440-57-5	0.185	0.23	0.23	2305	2305
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1237
plastics	plastics	epoxy resin	-	5.359	6.68		66780	
		silicondioxide	60676-86-0	44.162	55.03	61.83	550316	618333
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10142	10142
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1116	1116
glue	plastics	acrylic resin	-	0.119	0.15		1486	
		silver	7440-22-4	0.423	0.53	0.68	5269	6755
*deviation	< 10%					Sum in total:	100,00	1000000

### Important Remarks:

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